NEW CHIP SEALS SHOULDN'T MEAN NEW WINDSHIELDS.

-eFog HP HIGH-PERFORMANCE

For every chip seal application, the ability to keep aggregate on the road and off of vehicles is essential. Ergon's eFog HP is a trackless, high-performance fog seal developed to minimize aggregate loss by serving as the cohesive solution for locking down aggregate on newly chip sealed surfaces.

Enjoy your new road, and your current windshield, with eFog HP.





Minimize Aggregate Loss.

Ergon's new eFog HP is a trackless fog seal that locks down aggregate on newly chip sealed surfaces, prevents raveling and delays aging on dense-graded hot mix. It also provides a quick return to traffic and increases durability.

REDUCES WINDSHIELD DAMAGE

eFog HP helps lock down aggregate following new chip seal applications, minimizing damage to windshields while extending the life of the chip sealed surface.

TRACKLESS

This high-performance fog seal is trackless, meaning cleaner and more efficient production as the emulsion stays on the road and off of equipment and vehicles.

QUICK RETURN TO TRAFFIC

Due to its trackless and quick-breaking properties, traffic can be returned to the surface sooner after an eFog HP application than a conventional fog seal.

